

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-4. (Canceled)

5. (Currently amended) A method for producing a solar cell module comprising:

~~a step for providing a plurality of solar cell elements each including a semiconductor substrate, having a front surface electrode formed on a light-receiving surface of the a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate; and~~

~~connection tabs for interconnecting the surface electrode on the light-receiving surface and the back surface electrode on the non-light receiving surface of the solar cell elements;~~

~~wherein a first solder layer for connecting the surface electrode to the connection tab on the light receiving surface and a second solder layer for connecting the back surface electrode to the connection tab on the non-light receiving surface have different melting points~~

a step for connecting a first connection tab to the front surface electrode of one of the solar cell elements, through a first solder layer;

a step for connecting a second connection tab to the back surface electrode of another of the solar cell elements, through a second solder layer having a different melting point than the first solder layer; and

a step for connecting the first connection tab to the second connection tab.

6. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the first solder layer ~~with has a~~ higher melting point ~~is a than the~~ second solder layer that covers one of the surface electrode on the light receiving surface of one of the solar cell elements and the back surface electrode on the non-light receiving surface of another one of the solar cell elements adjacent thereto that is connected to the connection tabs temporally earlier than the other one.
7. (Currently amended) The method for producing a solar cell module according to claim 6, wherein the first solder layer ~~with higher melting point~~ is substantially free of lead.
8. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the first or the second connection tabs ~~tab are is~~ provided with a through holes ~~hole at a~~ connection areas ~~area~~ between the connection tabs ~~tab~~ and the front surface electrodes electrode or the back surface electrodes electrode.
9. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the connection tabs are connected to a common connection line by means of a solder, and the connection tabs are provided with through holes at connection areas between the connection tabs and the common connection line.
10. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the connection tabs are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the connection tabs.

11. (Currently amended) The method for producing a solar cell module according to claim 5, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

12. (Currently amended) The method for producing a solar cell module according to claim 5, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

13-22. (Canceled)

23. (New) The method for producing a solar cell module according to claim 5, further comprising coating a surface of the electrode with the solder layer before the step for connecting a first connection tab to the front surface electrode of one of the solar cell elements, through a first solder layer; the step for connecting a second connection tab to the back surface electrode of another of the solar cell elements, through a second solder layer having a different melting point than the first solder layer; and the step for connecting the first connection tab to the second connection tab.

24. (New) The method for producing a solar cell module according to claim 5, further comprising coating a surface of the connection tab with the solder layer before the step for connecting a first connection tab to the front surface electrode of one of the solar cell elements, through a first solder layer; the step for connecting a second connection tab to the back surface electrode of another of the solar cell

elements, through a second solder layer having a different melting point than the first solder layer; and the step for connecting the first connection tab to the second connection tab.

25. (New) A method for producing a solar cell module, comprising:

a step for providing a solar cell element having a front surface electrode formed on a light-receiving surface of a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate;

a step for connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and

a step for connecting a second connection tab to an electrode of the solar cell element to which the first connection tab is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above step for connecting the first connection tab.

26. (New) The method for producing a solar cell module according to claim 25, wherein the first solder layer is substantially free of lead.

27. (New) The method for producing a solar cell module according to claim 25, wherein the first or the second connection tab is provided with a through hole at a connection area between the connection tab and the front surface electrode or the back surface electrode.

28. (New) The method for producing a solar cell module according to claim 25, wherein the connection tabs are connected to a common connection line by means of

a solder, and the connection tabs are provided with through holes at connection areas between the connection tabs and the common connection line.

29. (New) The method for producing a solar cell module according to claim 25, wherein the connection tabs are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the connection tabs.

30. (New) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

31. (New) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

32. (New) The method for producing a solar cell module according to claim 26, further comprising coating a surface of the electrode with the solder layer before the step for connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and the step for connecting a second connection tab to an electrode of the solar cell element to which the first connection tab is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above step for connecting the first connection tab.

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33. (New) The method for producing a solar cell module according to claim 26, further comprising coating a surface of the connection tab with the solder layer before the step for connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and the step for connecting a second connection tab to an electrode of the solar cell element to which the first connection tab is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above step for connecting the first connection tab.